

SOT1981-1

FM8, flange mount package, 8 terminals, 1.02 mm pitch, 10.26 mm x 10.26 mm x 3.81 mm body

8 November 2019

Package information

1 Package summary

Terminal position code	S (single)
Package type descriptive code	FM8
Mounting method type	F (flange mount)
Issue date	29-10-2019
Manufacturer package code	98ASA01217D

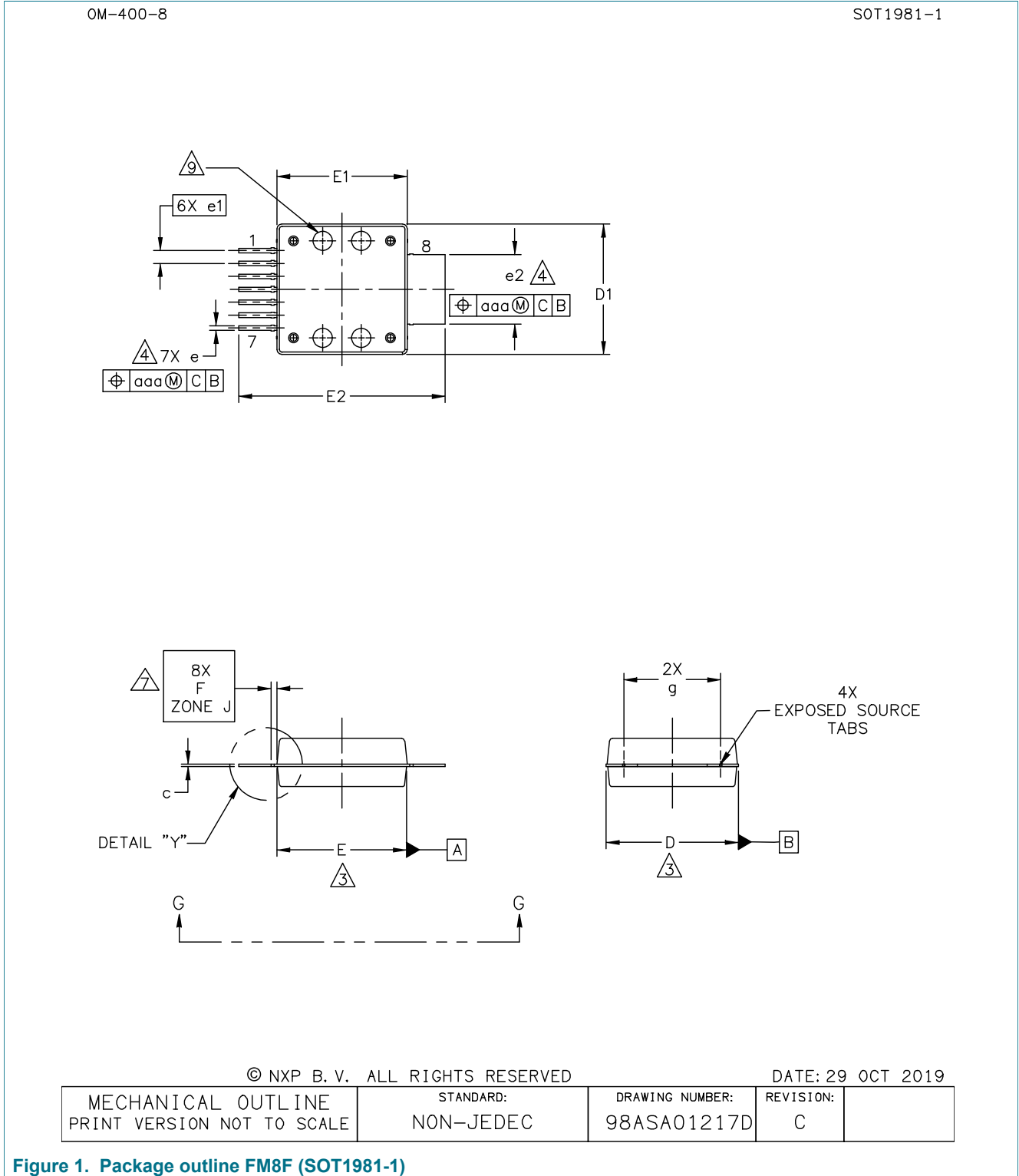
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	10.21	10.26	10.31	mm
package width	10.21	10.26	10.31	mm
seated height	3.73	3.81	3.89	mm
nominal pitch	-	1.02	-	mm
actual quantity of termination	-	8	-	

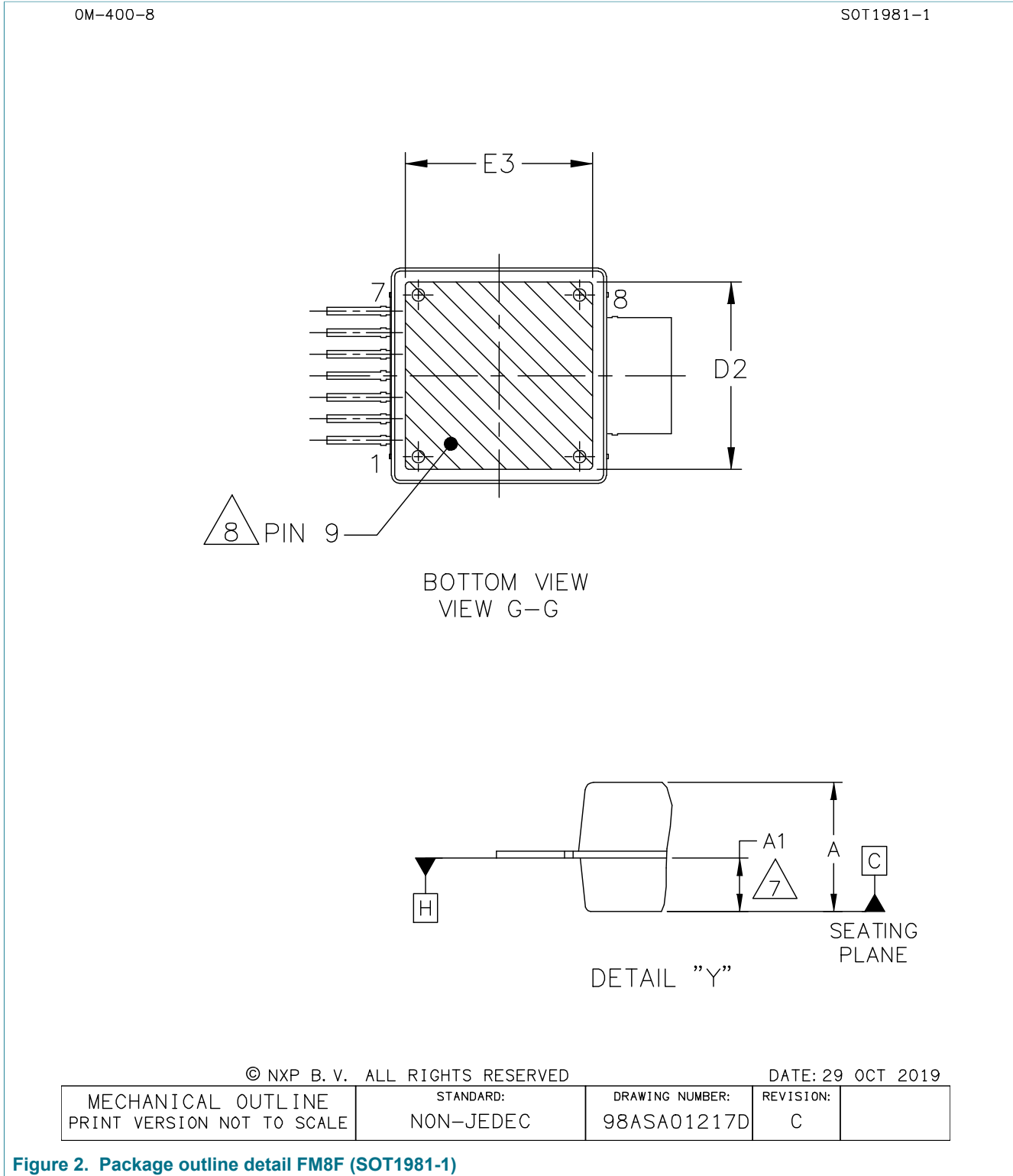


FM8, flange mount package, 8 terminals, 1.02 mm pitch, 10.26 mm x 10.26 mm x 3.81 mm body

2 Package outline



FM8, flange mount package, 8 terminals, 1.02 mm pitch, 10.26 mm x 10.26 mm x 3.81 mm body



FM8, flange mount package, 8 terminals, 1.02 mm pitch, 10.26 mm x 10.26 mm x 3.81 mm body

OM-400-8

SOT1981-1

NOTES:

1. CONTROLLING DIMENSION: INCH
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DIMENSIONS D & E DOES NOT REFLECT PLASTIC OR METAL PROTRUSIONS OF PACKAGE PART LINE. ALLOWABLE PROTRUSION IS .006 INCH (0.15 MM).
4. DIMENSIONS e & e2, DO NOT INCLUDE DAMBAR PROTRUSIONS. ALLOWABLE PROTRUSIONS IS .005 INCH (0.13 MM).
5. DATUM PLANE H IS LOCATE AT THE BOTTOM OF THE LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
6. DATUMS A AND B TO BE DETERMINED AT DATUM PLANE H.
7. DIMENSION A1 APPLIES WITHIN ZONE J ONLY.
8. HATCHING AREA REPRESENTS EXPOSED AREA OF THE HEATSINK. DIMENSIONS D1 AND E1 REPRESENT THE VALUES BETWEEN THE TWO OPPOSITE POINTS ALONG THE EDGES OF THE EXPOSED AREA OF HEAT SLUG.
9. DIMPLED HOLE REPRESENTS PIN 1.

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	.147	.153	3.73	3.89	e1	.040 BSC		1.02 BSC	
A1	.059	.065	1.50	1.65	e2	.213	.219	5.41	5.56
D	.398	.402	10.11	10.21	c	.007	.009	0.18	0.23
D1	.402	.406	10.21	10.31	g	.295	.305	7.49	7.75
D2	.343	.353	8.71	8.97	aaa	.005		0.13	
E	.398	.402	10.11	10.21					
E1	.402	.406	10.21	10.31					
E2	.636	.644	16.15	16.36					
E3	.343	.353	8.71	8.97					
F	.025 BSC		0.635 BSC						
e	.011	.017	0.28	0.43					

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DATE: 29 OCT 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01217D	REVISION: C	
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Figure 3. Package outline note FM8F (SOT1981-1)

3 Legal information

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